DNA 1170 Series













Main Features

- Intel Atom® C5315/C5325 processor
- 2 x DDR4 SODIMM, up to 16GB
- 8 x 1GbE RJ45 ports
- 4 x SFP+ ports

- 2 x 65W AC power adapters
- Supports Wi-Fi 6E (optional)
- Supports LTE/5G (optional)
- 4 x 1GbE RJ45 ports with 2 x bypass pairs

Product Overview

DNA 1170 Series is NEXCOM cyber security appliance offering server-grade performance in a desktop form factor. Powered by Intel Atom® C5000 series processor with up to 8 cores and embedded Intel® QAT feature, it features eight 1GbE copper and four 10GbE fiber ports to meet various requirements for fixed wired connectivity. To meet the increasing demand for wireless connectivity, a dedicated SKU reserves 5G/LTE and/or Wi-Fi 6E modules installation, expanding the maximal quantity of connected devices and adding wireless routes. Optional storage expansion with 2.5" SSD and enabling four ports with bypass function broaden available use cases and application scenarios.

Specifications

Main Board

- Intel Atom® C5000 processor w/ QAT
 - Intel Atom® processor C5315, BGA type, 4 cores/2.4 GHz for DNA 1170
 - Intel Atom® processor C5325, BGA type, 8 cores/2.4 GHz for DNA 1170A
 - Intel Atom® processor C5325, BGA type, 8 cores/2.4 GHz for DNA 1170W

Main Memory

• 2 x DDR4 2933 SODIMM, up to 16GB

Storage

- 1 x M.2 2242 for SATA 3.0
- 2 x 2.5" SSD SATA 3.0 (DNA 1170W)

Interface External

- Button: power and reset
- LED: status/MGMT/HA/PWR1/PWR2/SSD/LAN

- LED (optional): bypass/5G LTE/Wi-Fi
- 1 x RJ45 console port
- 3 x USB 3.0 connector
- 1 x Nano SIM slot (DNA 1170W)
- 1 x 1G RJ45 management port
- 8 x 1GbE RJ45 ports
- 4 x 1GbE RJ45 ports with 2 x bypass pairs
- 4 x SFP+ ports
- 1 x Fixed smart fan
- 2 x Power inlets
- 6 x Antenna holes (4 x antennas for 5G LTE, 2 x antennas for Wi-Fi 6E) (DNA 1170W)

Interface Internal

- 1 x mini-PCIe slot for Wi-Fi module (DNA 1170W)
- 1 x M.2 3042 Key B for 5G/LTE module (DNA 1170W)
- 1 x TPM header





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Power

• 2 x 65W 19V AC power adapters

Dimension and Weight

- Chassis dimension (mm): 340 x 250 x 44 (W x D x H)
- Package dimension(mm): 436 x 346 x 198 (W x D x H)
- Without packing: 2.9kgWith packing: 4.3kg

Environment

- Operating temperature: 0°C~40°C
- Storage temperature: -20°C~80°C
- Relative humidity: 10%~90% non-condensing

Certification

• CE/FCC class B

Ordering Information

• DNA 1170 (P/N: TBD)

Intel Atom® processor C5315, BGA type 4 cores/2.4 GHz, w/ 4 x SFP+ & 8 x 1GbE RJ45 ports

• DNA 1170A (P/N: 10L00117001X0)

Intel Atom® processor C5325, BGA type 8 cores/2.4 GHz, w/ 4 x SFP+ & 8 x 1GbE RJ45 ports

• DNA 1170W (P/N: TBD)

Intel Atom® processor C5325, BGA type 8 cores/2.4 GHz, w/ 4 x SFP+ & 8 x 1GbE RJ45 ports, 1 x mini-PCIe slot for Wi-Fi module & 1 x M.2 3042 Key B for 5G/LTE module

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